ABSTRACT

A semiconductor device comprises a plurality of semiconductor chips (20, 30) having electrodes (22, 32) and aligned in the horizontal direction; a substrate (10) on which is formed an interconnect pattern (12) having bonding portions (14) connected to the electrodes (22, 32) of the semiconductor chips (20, 30) and lands (16) connected to the bonding portions (14), and external electrodes (40) provided on the lands (16) and connected to the electrodes (22, 32) through an interconnect pattern (12).